

Research and Technology Center Detector Physics

**FTD BONN**



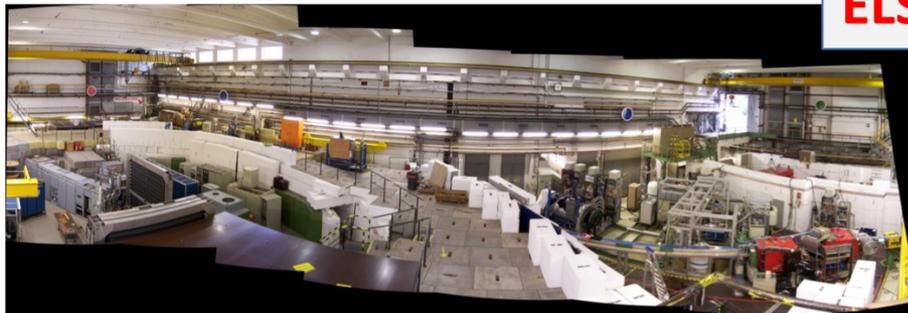
# Center for Detector and Accelerator Research (CEDAR)

- hosts 10 Groups from 2 institutes from
  - High Energy & Hadron Physics
    - LHC: ALICE, ATLAS, LHCb
    - Belle II, COMPASS, CBELSA/TAPS  
BGO-OD, ILC, PANDA , AMBER, NA64
    - RD42, RD50, RD53, RD51
  - Photonics



**FTD building**

- 2 local accelerators
  - electron stretcher ring ELSA (3.5 GeV e-)
  - cyclotron 15 MeV p (and ions)



**ELSA**



**cyclotron**

# “In-house” test-beams and irradiation

Test-beam area at ELSA (PI)



Proton cyclotron (HISKP)



Testing of detector components  
in the ELSA electron beam

15 MeV p irradiation  
 $10^{16} n_{eq}/cm^2$   
in about 2 hrs



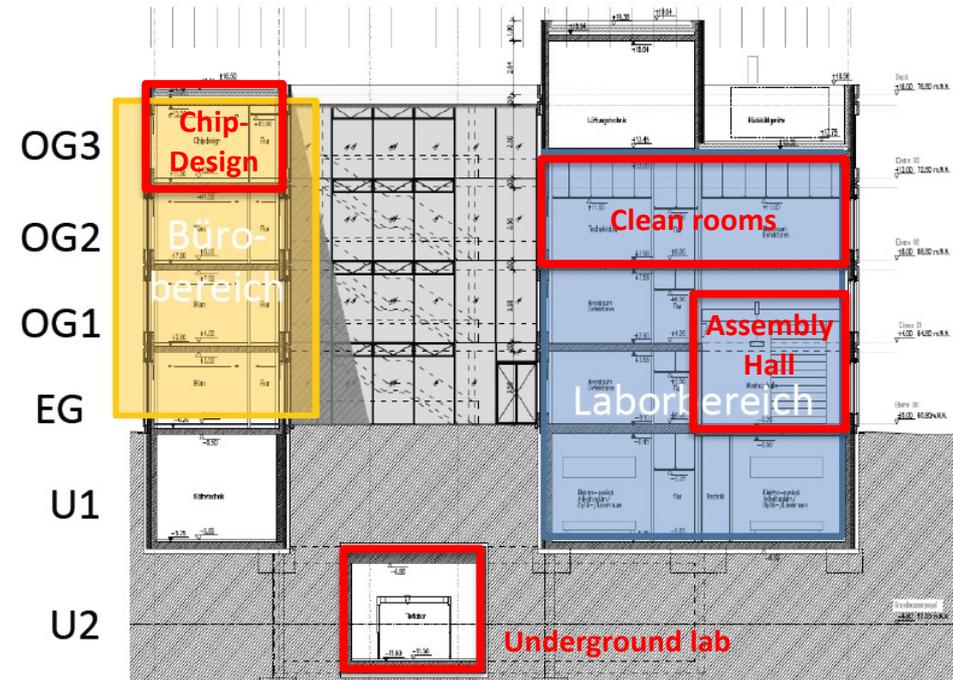
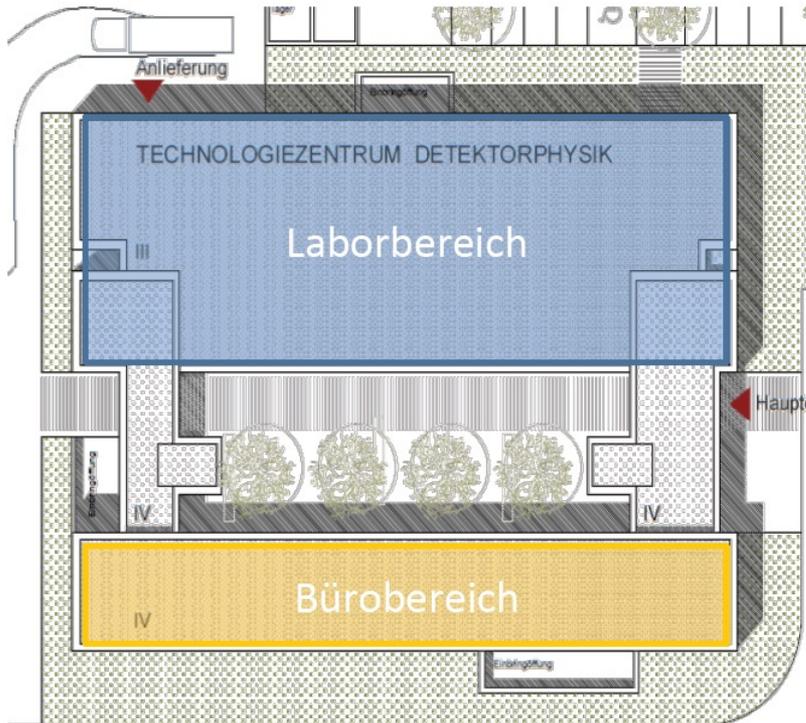
# FTD building

## Lab space

- 2010 m<sup>2</sup>
- 4 Levels + Underground Laboratory
- 360 m<sup>2</sup> clean rooms (ISO 5, 6, 7)

## Office space:

- 880 m<sup>2</sup>
- 4 Levels



# Impressions



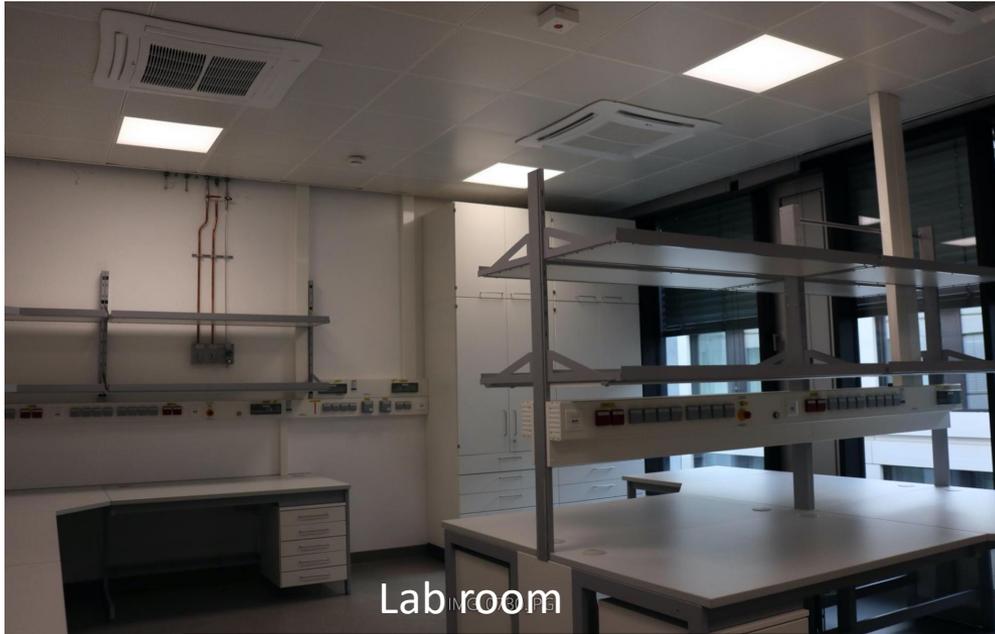
Main entrance

# Impressions



Inner courtyard (atrium)

# Impressions



Lab room



Office



Chip design

# Impressions



ISO-7 clean room

IMG\_0740.JPG



IMG\_0746.JPG



ISO-5 clean room

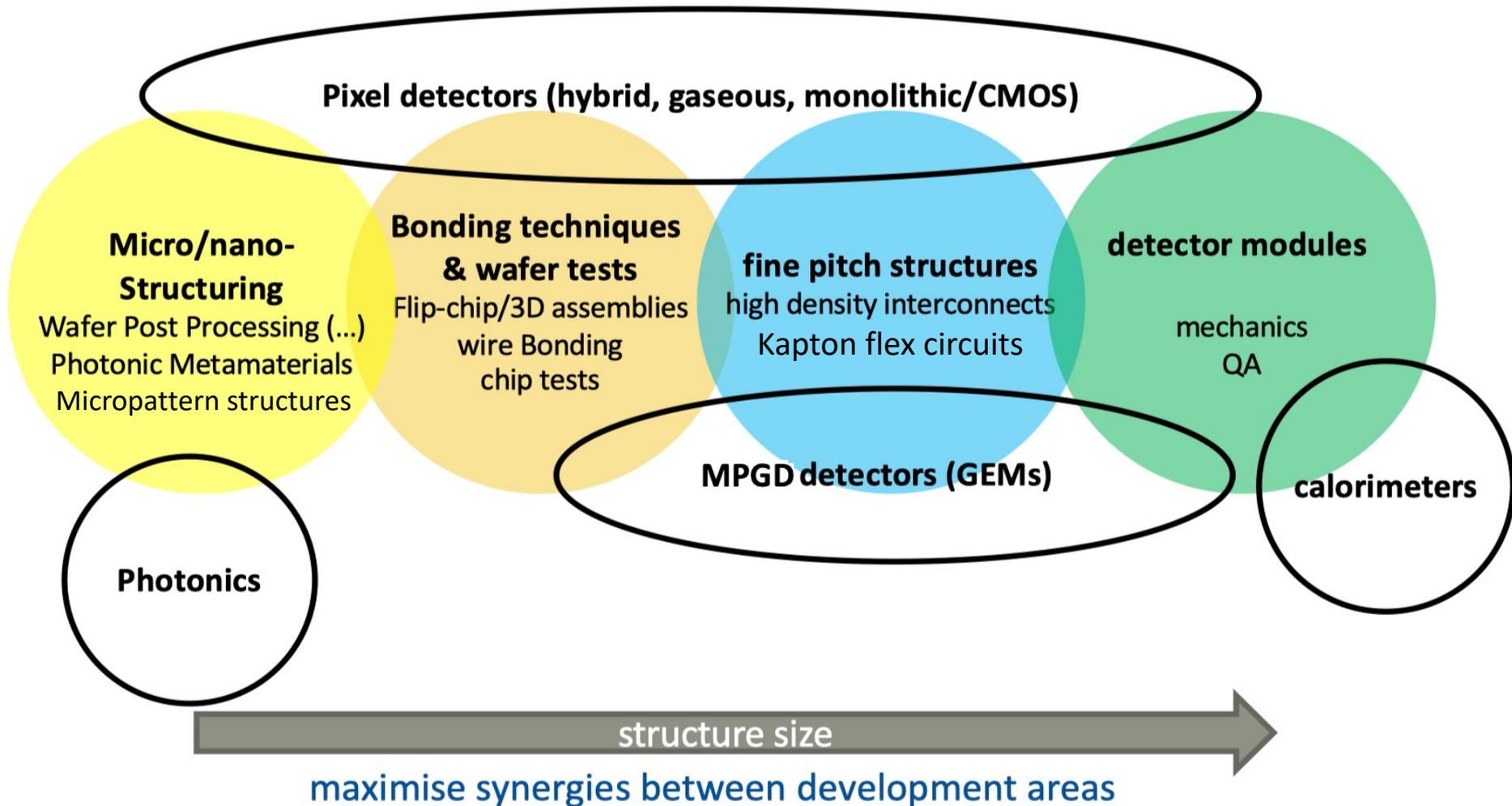
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# Impressions

Assembly hall



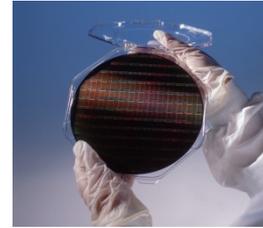
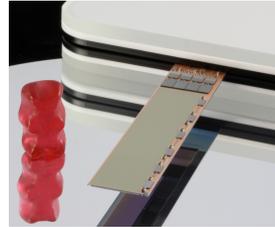
# Target technologies and applications



# Detector R&D at the FTD

## Silicon pixel detectors

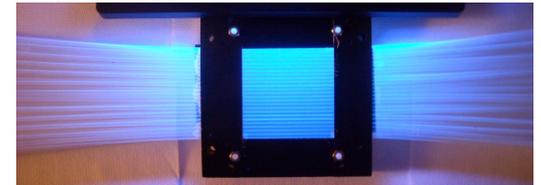
- ATLAS
- BELLE II



## Chip design

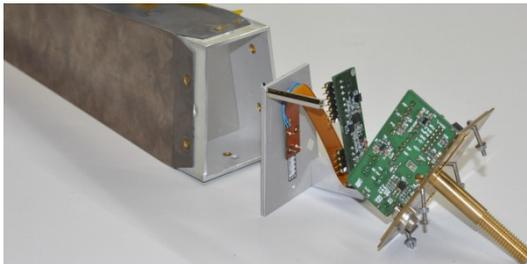
## Scintillating fibers

- BGO-OD
- CB-ELSA
- COMPASS

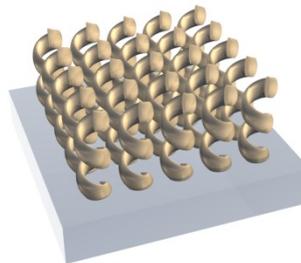


## High-resolution calorimeters

- CB-ELSA
- PANDA

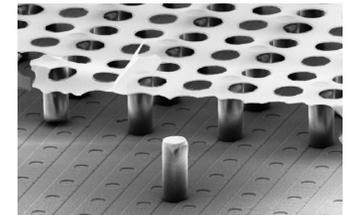
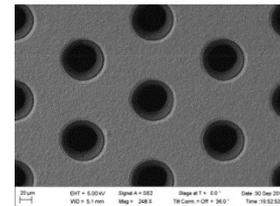


## Optical antennas



## Microstructured gas detectors

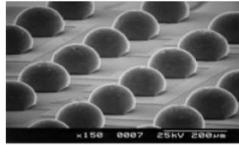
- ALICE
- ILC



# New equipment

## Solder ball placer

up to 8" wafers  
pitch  $\approx 100 \mu\text{m}$   
min  $\varnothing = 40 \mu\text{m}$



CR: PacTech

## X-ray inspection

precision  $< 1 \mu\text{m}$   
scan area (20cm<sup>2</sup>)



CR: Nikon

wafers, ball-bonding and inspection

## Wafer saw

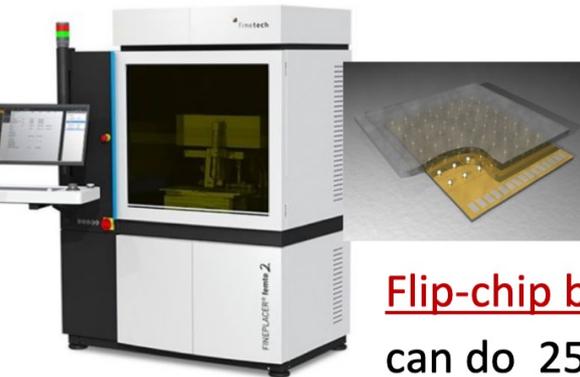
12" wafers



CR DISCO

## Flip-chip bonder

can do  $25 \mu\text{m}$  ( $\rightarrow 10 \mu\text{m}$ )  
AgSn bumps with  $< 1 \mu\text{m}$



CR FineTech

## 3D measuring machine

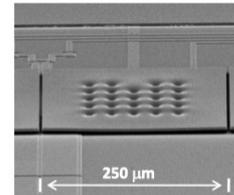
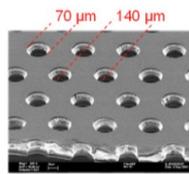
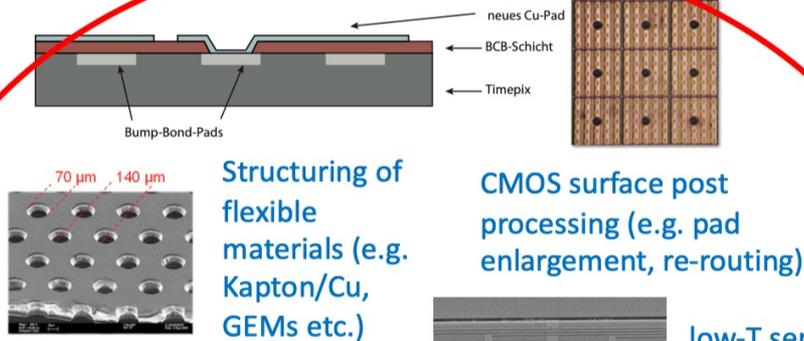
laser-based tracker  
contact-less  
1  $\mu\text{m}$  resolution



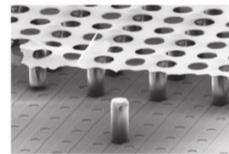
# New equipment

## Micro-structuring

### Plasma Etching



low-T sensors  
MMC, TES;  
SC structures,  
SQUIDS



Complex structures on top of CMOS chips (e.g. InGrid)

3 wet benches for chemistry and spin coating

### Sputtering



### Ion Etching



### Maskless Aligner





FORSCHUNG- UND  
TECHNOLOGIEZENTRUM  
DETEKTORPHYSIK

